

Data sheet

SAW filter
Small cell & femtocell
LTE band 8 downlink

Series/type: B9630

Ordering code: B39941B9630P810

Date: January 29, 2019

Version: 2.2

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A Qualcomm – TDK Joint Venture

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1 Application

- Low-loss RF filter for smallcells
- Usable pass band 35MHz

2 Features

- Package size 1.4±0.1 mm × 1.1±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

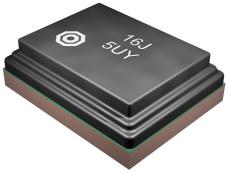
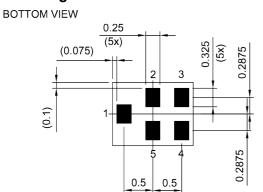


Figure 1: Picture of component with example of product marking.

3 Package



Pad and pitch tolerance ±0.05

4 Pin configuration

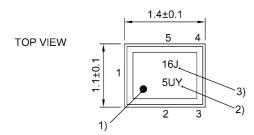
■ 1 Input

■ 4 Output

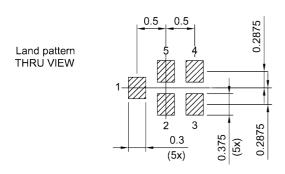
■ 2, 3, 5 Ground

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 19).

5 Matching circuit

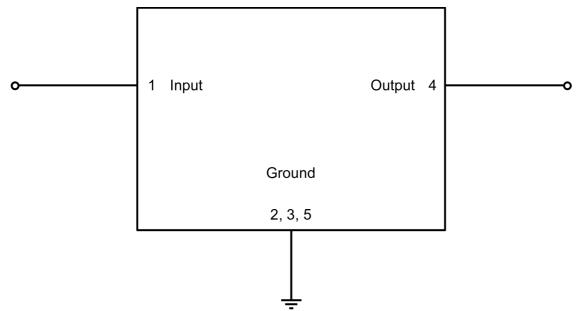


Figure 3: Schematic of matching circuit. No external matching components required.



6 Characteristics

Temperature range for specification $T_{\text{SPEC}} = -10 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$

 $\begin{array}{lll} \mbox{Input terminating impedance} & Z_{_{\rm IN}} & = 50 \ \Omega \\ \mbox{Output terminating impedance} & Z_{_{\rm OUT}} & = 50 \ \Omega \\ \end{array}$

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f _C	_	942.5	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	925 960	MHz		_	2.1	3.2	dB
Amplitude ripple (p-p)			Δα				
	925 960	MHz		_	1.0	2.2	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	925 960	MHz		_	1.9	2.3	
@ output port	925 960	MHz		_	1.9	2.3	
Maximum error vector magnitude			EVM _{max} 1)				
	927.4 957.6	MHz		_	2.5	6.0	%
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	50 791	MHz		40	43	_	dB
	791 821	MHz		43	46	_	dB
	832 862	MHz		40	49	_	dB
	880 915	MHz		30	36	_	dB
	1570 1606	MHz		35	52	_	dB
	1710 1785	MHz		35	58	_	dB
	1805 1880	MHz		35	54	_	dB
	1920 1980	MHz		35	50	_	dB
	2110 2170	MHz		35	46	_	dB
	2400 2500	MHz		30	41	_	dB
	2500 2570	MHz		30	40	_	dB
	2620 2690	MHz		30	39	_	dB
	5150 5850	MHz		20	27	_	dB

¹⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



Temperature range for specification

Input terminating impedance
Output terminating impedance

 $T_{\text{SPEC}} = -40 \,^{\circ}\text{C} \dots +95 \,^{\circ}\text{C}$

 $Z_{\text{IN}} = 50 \,\Omega$ $Z_{\text{OUT}} = 50 \,\Omega$

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f _C	_	942.5	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	925 960	MHz		_	2.1	4.2	dB
Amplitude ripple (p-p)			Δα				
	925 960	MHz		_	1.0	3.2	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	925 960	MHz		_	1.9	2.4	
@ output port	925 960	MHz		_	1.9	2.4	
Maximum error vector magnitude			$\text{EVM}_{\text{max}}^{-1)}$				
	927.4 957.6	MHz		_	2.5	10	%
Minimum attenuation			α_{min}				
	50 791	MHz		40	43	_	dB
	791 821	MHz		43	46	_	dB
	832 862	MHz		40	49	_	dB
	880 915	MHz		26	36	_	dB
	1570 1606	MHz		35	52	_	dB
	1710 1785	MHz		35	58	_	dB
	1805 1880	MHz		35	54	_	dB
	1920 1980	MHz		35	50	_	dB
	2110 2170	MHz		35	46	_	dB
	2400 2500	MHz		30	41	_	dB
	2500 2570	MHz		30	40	_	dB
	2620 2690	MHz		30	39	_	dB
	5150 5850	MHz		20	27	_	dB

¹⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.



7 Maximum ratings

Operable temperature	T _{OP} = -40 °C +95 °C	
Storage temperature	T _{STG} ¹⁾ = -40 °C +95 °C	
DC voltage	$ V_{DC} ^{2)} = 0 V$	
ESD voltage	$V_{ESD}^{3)} = 100 \text{ V}$	Machine model.
Input power @ input port: 925 960 MHz	P _{IN} = 15 dBm ⁴⁾	5 MHz LTE downlink signal (25 RB) for 50000 h @ 55 °C. Source and load impedance 50Ω

Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁴⁾ Expected Life Time according to accelerated power durability simulation and wear out models.

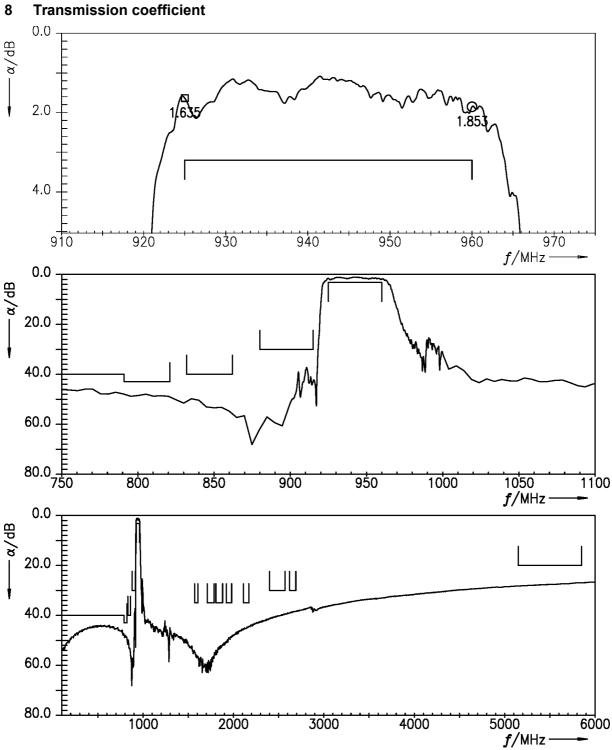
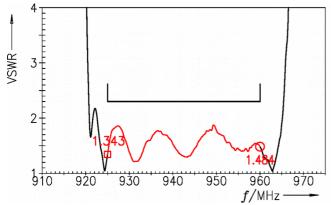


Figure 4: Attenuation .

9 Reflection coefficients



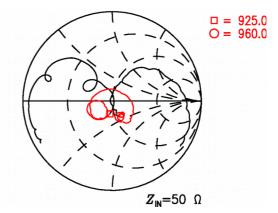
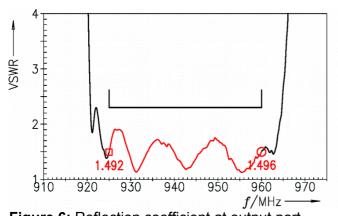


Figure 5: Reflection coefficient at input port.



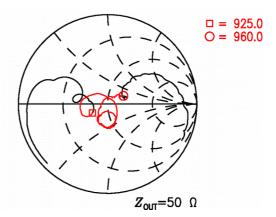


Figure 6: Reflection coefficient at output port.

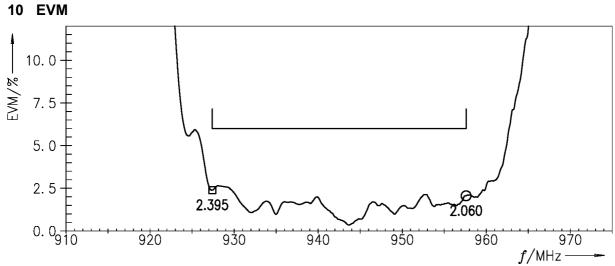


Figure 7: Error vector magnitude .

11 Packing material

11.1 Tape

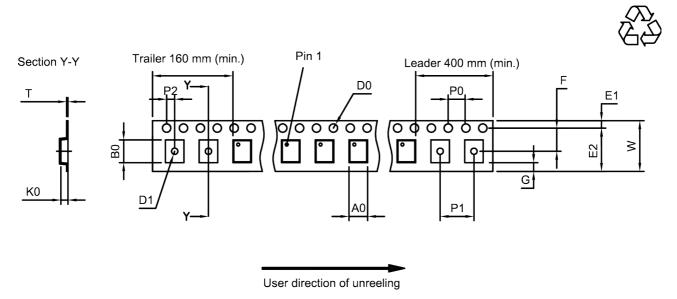


Figure 8: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.27±0.05 mm	- -	E ₂	6.25 mm (min.)	-	P ₁	4.0±0.1 mm
B ₀	1.57±0.05 mm	-	F	3.5±0.05 mm	-	P ₂	2.0±0.05 mm
D_0	1.5+0.1/-0 mm	-	G	0.75 mm (min.)		Т	0.25±0.03 mm
D ₁	0.5±0.1 mm	-	K ₀	0.62±0.05 mm	-	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	-	P ₀	4.0±0.1 mm	-		

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

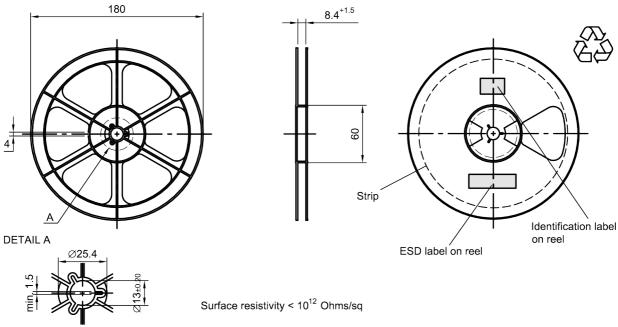


Figure 9: Drawing of reel (first-angle projection) with diameter of 180 mm.

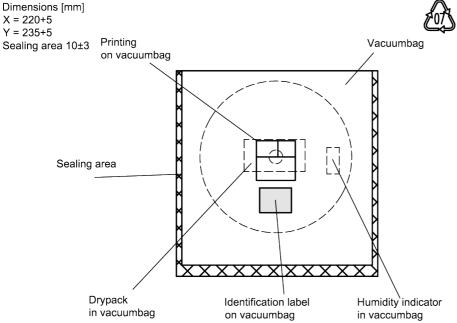


Figure 10: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

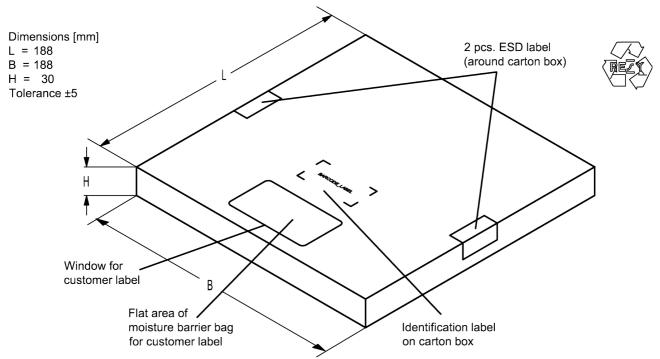


Figure 11: Drawing of folding box for reel with diameter of 180 mm.



12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x 32^2 + 6 x 32^1 + 18 (=J) x 32^0 = 1234

The BASE32 code for product type B9630 is 9CY.

■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$ 12345

Adopted BASE32 code for type number					
Decimal	Base32	Decimal	Base32		
value	code	value	code		
0	0	16	G		
1	1	17	Н		
2	2	18	J		
3	3	19	K		
4	4	20	M		
5	5	21	N		
6	6	22	Р		
7	7	23	Q		
8	8	24	R		
9	9	25	S		
10	Α	26	Т		
11	В	27	V		
12	С	28	W		
13	D	29	X		
14	E	30	Y		
15	F	31	Z		

Adopted BASE47 code for lot number					
Decimal	Base47	Decimal	Base47		
value	code	value	code		
0	0	24	R		
1	1	25	S		
2	2	26	Т		
3	3	27	U		
4	4	28	V		
5	5	29	W		
6	6	30	Х		
7	7	31	Y		
8	8	32	Z		
9	9	33	b		
10	Α	34	d		
11	В	35	f		
12	С	36	h		
13	D	37	n		
14	E	38	r		
15	F	39	t		
16	G	40	V		
17	Н	41	١		
18	J	42	?		
19	K	43	{		
20	L	44	}		
21	М	45	<		
22	N	46	>		
23	Р				

Table 2: Lists for encoding and decoding of marking.



13 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T _{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature <i>T</i>	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

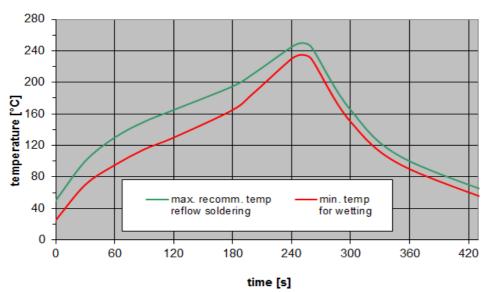


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.



14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

Ordering code	Packing unit
B39941B9630P810	5000 pcs

Table 4: Ordering codes and packing units.



15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.



16 Important notes

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